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SPECIFICATION

VXT397FBWS-01

☒ Preliminary Specification

☐ Final Specification



Approved By:

Date:

Records of Revision

[illegible]

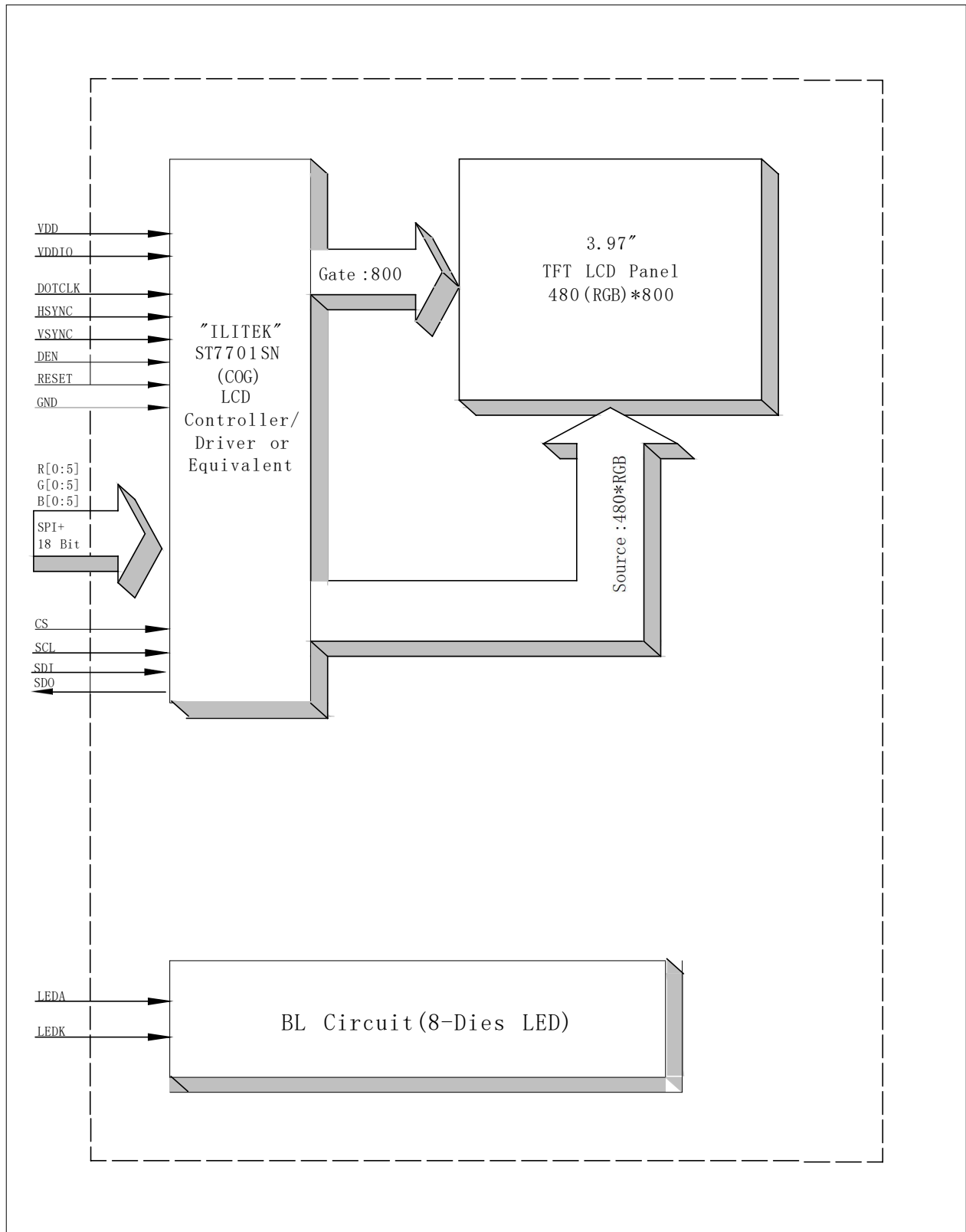
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1. General Specification

Item	Contents	Unit
LCD type	TFT/TRANSFLECTIVE	
Module size (W*H*T)	57.14*96.85*2.00	mm
Active size (W*H)	51.84*86.40	mm
Pixel pitch (W*H)	0.108*0.108	mm
Number of dots	480*800	
Driver IC	ST7701SN-G5	
Interface type	18-Bit RGB+SPI	
Top polarizer type	Anti-Glare	
Recommend viewing direction	All	O'clock
Gary scale inversion direction	-	O'clock
Backlight type	8-Dies white LED	
Touch panel type	Without	

3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	YU	No connect.
2	XL	No connect.
3	YD	No connect.
4	XR	No connect.
5	LED_K	Cathode of LED back light.
6	GND	Power ground.
7	LED_A	Anode of LED back light.
8	VDD	Power supply for analog.
9	VDD	Power supply for analog.
10	VDDIO	Power supply for I/O system.
11	VDDIO	Power supply for I/O system.
12	CS	A chip select signal. Low: the chip is selected and accessible High: the chip is not selected and not accessible Fix to VDDI or DGND level when not in use.
13	SCL	Serial clock input for SPI interface. Fix to VDDI or GND level when no in use.
14	SDI	Serial data input pin for SPI interface. Fix to GND level when no in use.
15	SDO	Serial data output pin used for the SP interface. Leave the pin open when no in use.
16	B0	Blue data.
17	B1	Blue data.
18	B2	Blue data.
19	B3	Blue data.
20	B4	Blue data.
21	B5	Blue data.
22	G0	Green data.
23	G1	Green data.
24	G2	Green data.
25	G3	Green data.
26	G4	Green data.
27	G5	Green data.
28	R0	Red data.
29	R1	Red data.
30	R2	Red data.
31	R3	Red data.
32	R4	Red data.
33	R5	Red data.
34	DEN	Data enable signal fr RGB interface operation Low:access enabled; High:access inhibited;

		Fix to VDDI or DGND level when not in use.
35	DOTCLK	Dot clock signal for RGB interface operation Fix to VDDI or DGND level when not in use.
36	HSYNC	Line synchronizing signal for RGB interface operation Fix to VDDI or DGND level when not in use.
37	VSYNC	Frame synchronizing signal for RGB interface operation Fix to VDDI or DGND level when not in use.
38	RESET	The external reset input Initializes the chip with a low input.Be sure to execute a power-on reset after supplying power.
39	GND	Power ground.
40	NC	No connect.
41	NC	No connect.
42	NC	No connect.
43	NC	No connect.
44	NC	No connect.
45	NC	No connect.

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.6	V
Supply voltage for logic	VDDIO	-0.3	4.6	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	2.5	2.8	3.6	V	
Supply Voltage for Logic	VDDIO	1.65	1.8/2.8	3.6	V	
Input Voltage	V _{IL}	0	-	0.3 VDDIO	V	
	V _{IH}	0.7 VDDIO	-	VDDIO		
Input leakage Current	I _{LKG}	-1		1	μA	

6.2 Backlight Driving Conditions

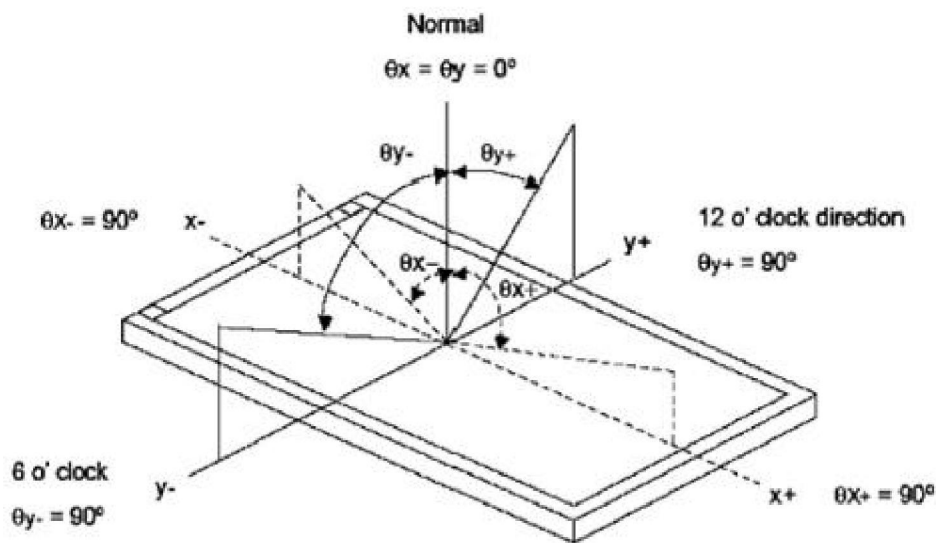
Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V _F	10.8	12.8	13.6	V	I _L =40mA
Current for LED Backlight	I _L		40		mA	
Power Consumption	P		0.512		W	
LED Life Time		30,000	50,000		Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25℃

7. Optical Characteristics

ITEM		SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
				MIN	TYP.	MAX		
Luminance		L	IL =40mA	100	130	180	cd/m ²	
Contrast Ratio		CR	$\theta=0^{\circ}$					
Response Time		T _{ON}	25°C				ms	
		T _{OFF}						
CIE Color Coordinate	Red	X _R	Viewing normal angle	0.3733	0.4133	0.4533		
		Y _R		0.2531	0.2931	0.3331		
	Green	X _G		0.2915	0.3315	0.3715		
		Y _G		0.3939	0.4339	0.4739		
	Blue	X _B		0.1387	0.1787	0.2187		
		Y _B		0.1333	0.1733	0.2133		
	White	X _W		0.2654	0.3054	0.3454		
		Y _W		0.2780	0.3180	0.3580		
Viewing Angle	Hor.	θ_{X+}	CR≥10	80	85		Degree	
		θ_{X-}		80	85			
	Ver.	θ_{Y+}		80	85			
		θ_{Y-}		80	85			
Uniformity	Un			80			%	

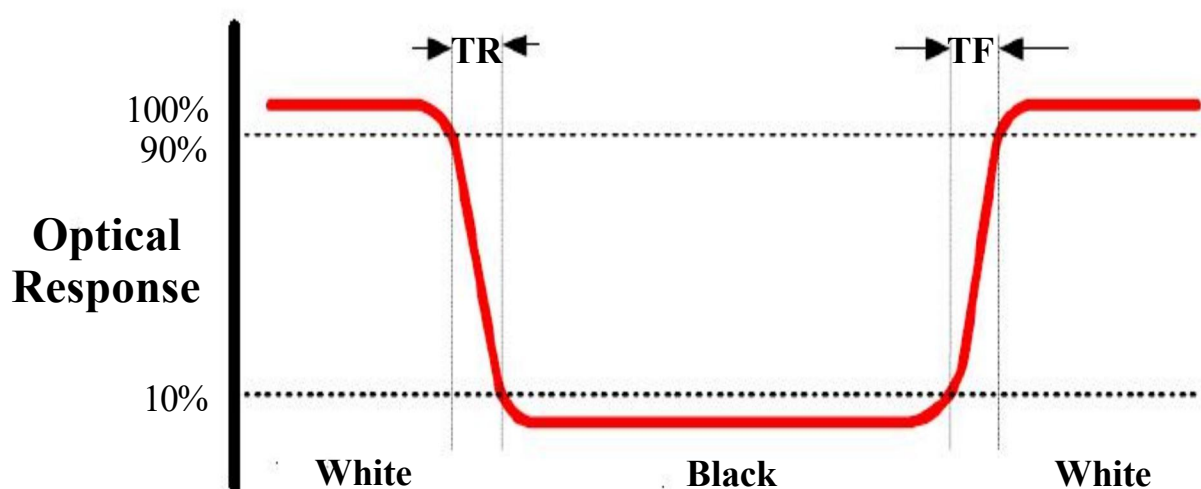
Note 1: Definition of Viewing Angle θ_x and θ_y :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

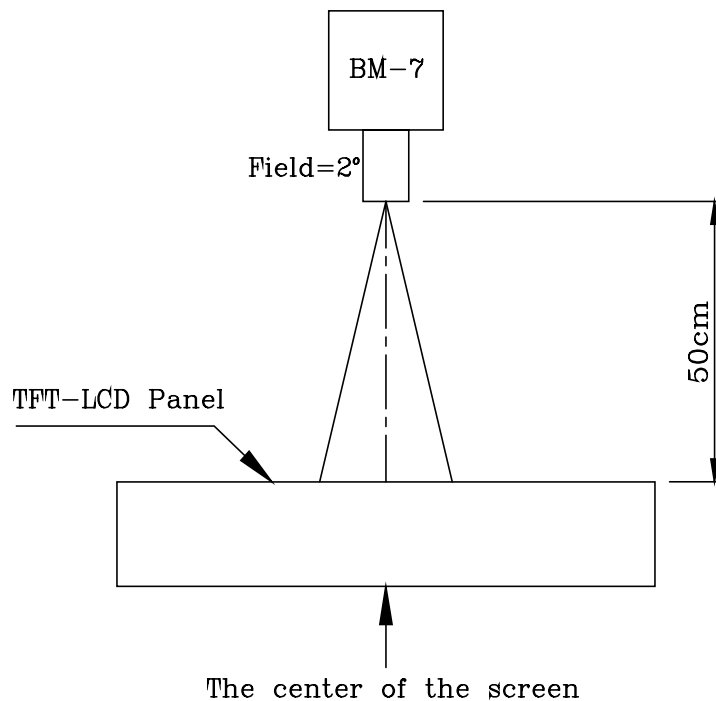
Note 3: Definition of Response Time(T_r , T_f)



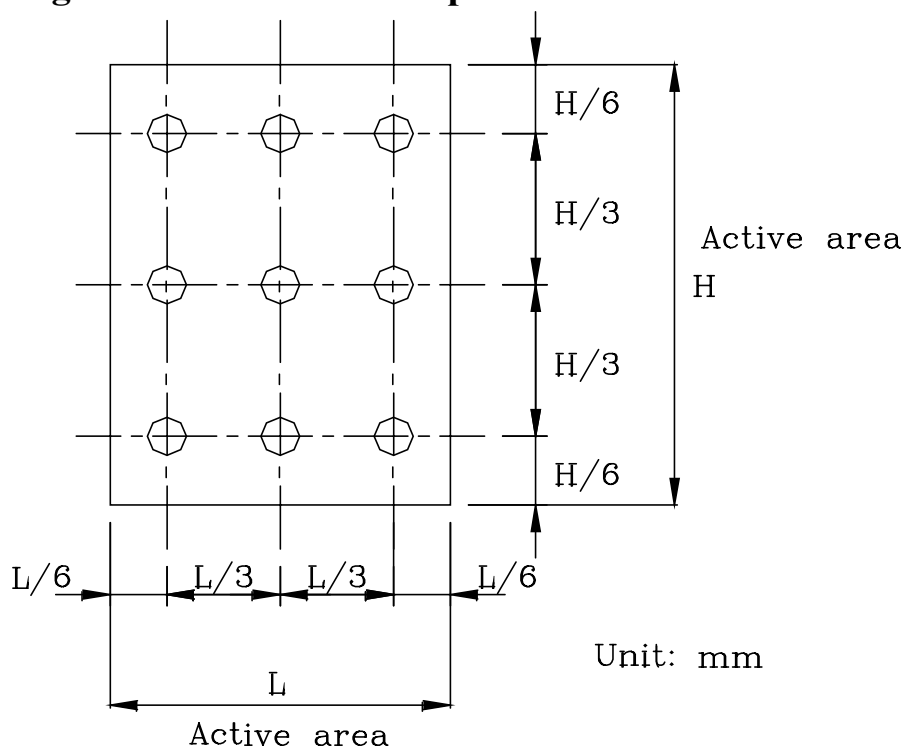
Note 4: Definition of Luminance

①The Brightness Test Equipment Setup

Field=2° (As measuring “black” image, field=2° is the best testing condition)

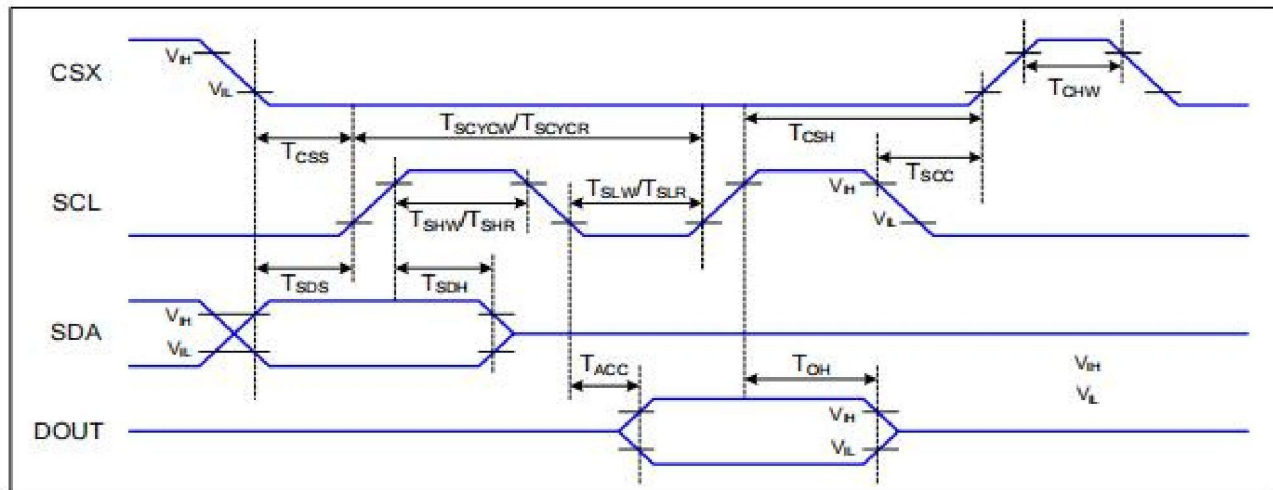


②The Brightness Test Point Setup



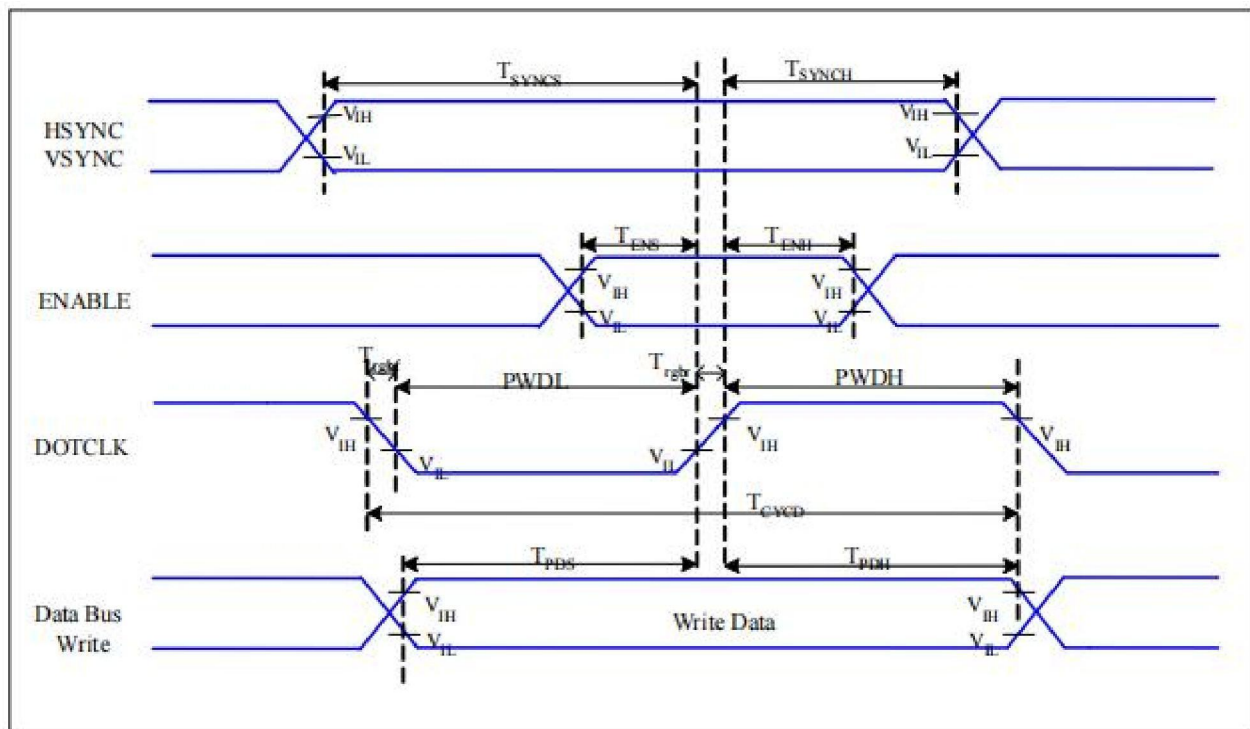
8. Timing Characteristics

8.1 Serial interface Characteristics(3-line serial)



Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	60		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T _{SDS}	Data setup time	10		ns	
	T _{SDH}	Data hold time	10		ns	
SDO (DOUT)	T _{ACC}	Access time	20	50	ns	Max: CL=30pF
	T _{OH}	Output disable time	50	50	ns	Min: CL=8pF

8.2 RGB Timing Characteristics



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYSN, HSYNCS Setup Time	5	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	5	-	ns	
	T_{ENH}	Enable Hold Time	5	-	ns	
DOTCLK	$PWDH$	DOTCLK High-level Pulse Width	15	-	ns	
	$PWDL$	DOTCLK Low-level Pulse Width	15	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	33	-	ns	
	T_{rghr}, T_{rghf}	DOTCLK Rise/Fall time	-	15	ns	
DB	T_{PDS}	PD Data Setup Time	5	-	ns	
	T_{PDH}	PD Data Hold Time	5	-	ns	

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature Operation	T _s = +70°C, 240 hours	IEC60068-21:2007 GB2423.2-2008
2	Low Temperature Operation	T _a = -20°C, 240 hours	IEC60068-2-1:2007 GB/2423.1-2008
3	High Temperature Storage	T _a = +80°C, 240 hours	IEC60068-21:2007 GB/2423.2-2008
4	Low Temperature Storage	T _a = -30°C, 240 hours	IEC60068-21:2007 GB/2423.1-2008
5	Storage at High Temperature and Humidity	T _a = +60°C, 90% RH max,240hours	IEC60068-2-78 :2001 GB/T2423.3—2006
6	Thermal Shock (non-operation)	-20°C 30 min~+60°C30 min, Change time:5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-214:1984, GB/2423.22-2002
7	ESD	C= 150pF,R=330Ω,5point/panel Air:±8Kv, 10times; Contact:±4Kv, 10times (Environment:15°C~35°C, 30%~60%.86Kpa~106Kpa)	IEC61000-42:2001 GB/T17626.2-2006
8	Package Drop Test	Height:80cm, 1corner,3 edges,6 surfaces	IEC60068-2-32:1990 GB/T2423.8—1995

Note1: T_s is the temperature of panel's surface.

Note2: T_a is the ambient temperature of sample.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}\text{C}$), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.
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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Victronix.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single Time.
- The defects classify of AQL as following:
Major defect: AQL = 0.65
Minor defect: AQL = 1.5
Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

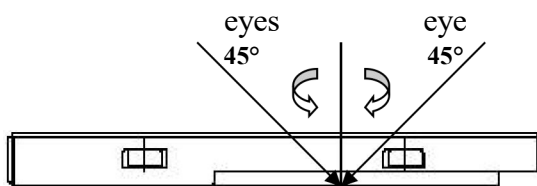
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

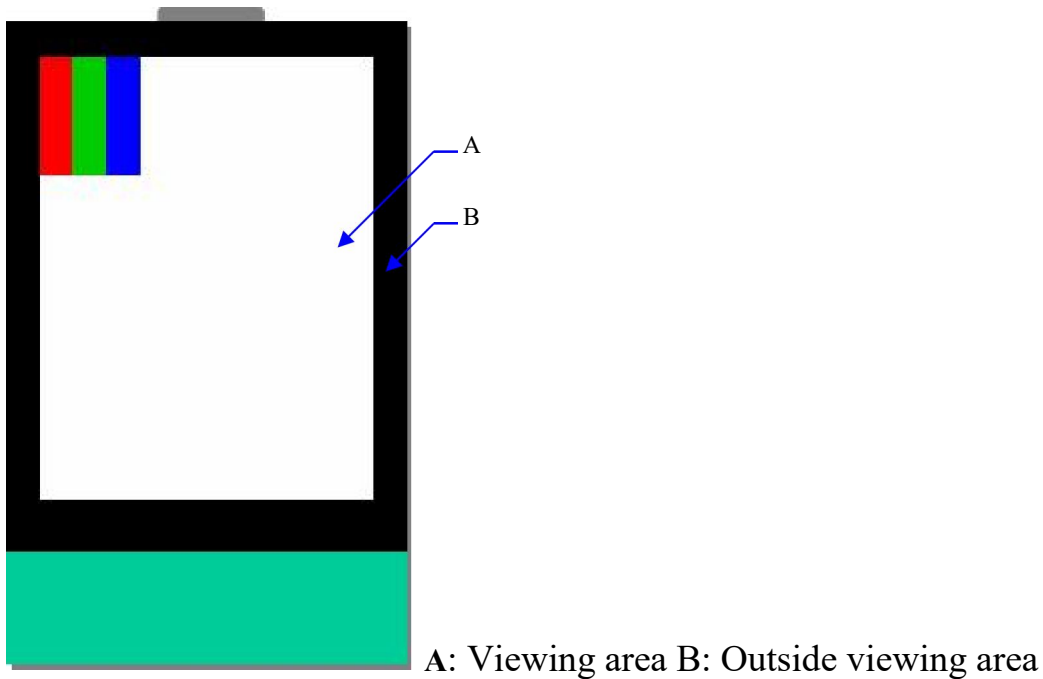
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 45° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



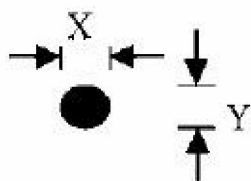
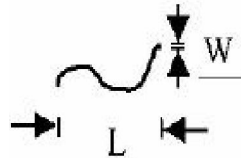
- Definition of area:

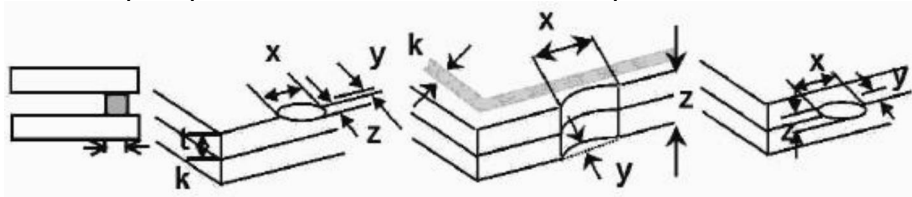
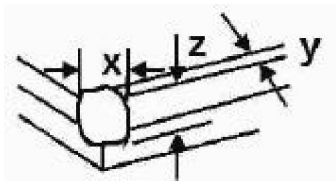


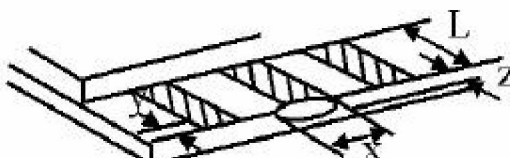
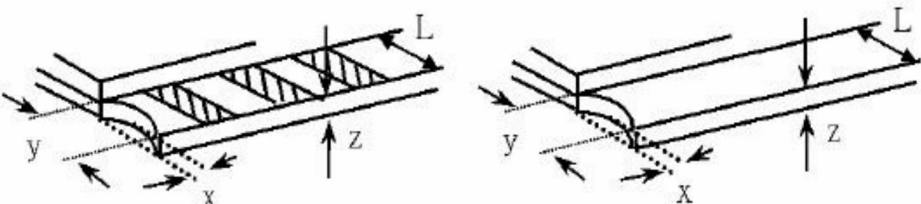
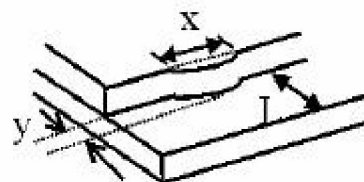
10.5.2 Basic principle

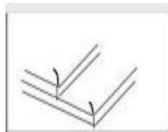
- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

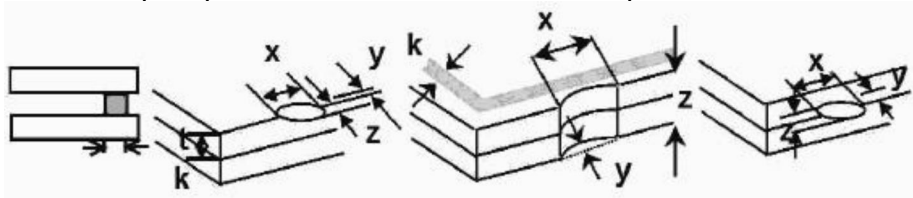
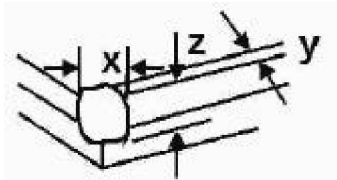
10.6 Inspection Specification

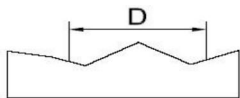
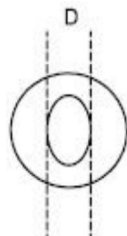
NO.	Item	Criterion	AQL			
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65			
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\cong 0.25\text{mm}$, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.	1.5			
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$		1.5		
			Size(mm)		Acceptable Q'ty	
			$\Phi \leq 0.10$		Accept no dense	
			$0.10 < \Phi \leq 0.20$		2	
			$0.20 < \Phi \leq 0.25$		2	
			$0.25 < \Phi \leq 0.30$		1	
			$0.30 < \Phi$		0	
		* Densely spaced: No more than two spots within 3mm.				
		3.2 Line type: (As following drawing)		1.5		
			Length(mm)		Width(mm)	Acceptable Q'ty
			---		$W \leq 0.02$	Accept no dense
			$L \leq 3.0$		$0.02 < W \leq 0.05$	2
$L \leq 2.5$	$0.03 < W \leq 0.08$					
---	$0.08 < W$		Rejection			
* Densely spaced: No more than two lines within 3mm.						

NO.	Item	Criterion			AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ (mm)	Acceptable Q'ty	1.5
			$\Phi \leq 0.20$	Accept no dense	
			$0.20 < \Phi \leq 0.50$	3	
			$0.50 < \Phi \leq 1.00$	2	
			$1.00 < \Phi$	0	
			Total Q'ty	3	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:			1.5
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
		⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 6.1.2 Corner crack:			
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	
		⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip			

NO.	Item	Criterion	AQL																
07	Glass crack	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:  <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq 0.5\text{mm}$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table> 7.2.2 Non-conductive portion:  <table><tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr><tr><td>$y \leq L$</td><td>$x \leq 1/8a$</td><td>$0 < z \leq t$</td></tr></table> ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged. 7.2.3 Substrate protuberance and internal crack  <table><tr><td>y: width</td><td>x: length</td></tr><tr><td>$y \leq 1/3L$</td><td>$X \leq a$</td></tr></table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	1.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with any extensive crack is not acceptable. 	1.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	1.5 1.5 0.65
10	Bezel	Bezel must comply with product specifications.	1.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	1.5 1.5 1.5 1.5 0.65 0.65
12	FPC	12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function , we judge accept.	1.5 1.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	1.5 0.65

NO.	Item	Criterion	AQL							
14	Touch Panel Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels: 	1.5							
		<table> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> <td rowspan="2"></td> </tr> <tr> <td>$Z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table>		z: Chip thickness	y: Chip width	x: Chip length		$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$
		z: Chip thickness		y: Chip width	x: Chip length					
		$Z \leq t$		$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$					
		⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 14.1.2 Corner crack: 								
		<table> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> <td rowspan="2"></td> </tr> <tr> <td>$z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table>		z: Chip thickness	y: Chip width	x: Chip length		$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$
		z: Chip thickness		y: Chip width	x: Chip length					
		$z \leq t$		$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$					
		⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip								

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	1.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable.	1.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	1.5										
18	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	1.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than $280\pm 10^{\circ}\text{C}$ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

No.	Item	Dimensions(mm)	Quantity	Remark
1	LCM Module	57.14*96.85*2.00	162PCS	
2	TRAY	375*330*15 (include 9pcs products/one tray)	20PCS	
3	SMALL CARTON	393*345*115 (include 81pcs products/one carton)	2PCS	
4	LARGE CARTON	430*380*270 (include 162pcs products/one carton)	1PCS	